

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICELIST OF REFERENCES CITED BY  
APPLICANT

(Use Several Sheets if Necessary)

Attorney Docket No.  
8733.307.00Application No.  
99,483

09/309 483

Applicant  
Oh-Nam KWONFiling Date  
November 13, 2000Group  
~~Unassigned~~ 2823

Date: May 14, 2001

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL*	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO
TUP	05-265040	10/1993	Japan	Abstract
TUP	02-271637	11/1990	Japan	Abstract
TUP	04-170519	6/1992	Japan	Abstract
TUP	06-097197	4/1994	Japan	Abstract
TUP	05-107553	4/1993	Japan	Abstract

## OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

TUP	Cecilia Y. Mak; MRS Bulletin; "Electroless Copper Deposition on Metals and Metal Silicides"; August 1994; (Pages 55-61)

EXAMINER *Shambran*

DATE CONSIDERED 1/16/02

\*EXAMINER: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

\*\*English-language abstract provided.